



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 20092

Generic Copy

Issue Date: 30-May-2013

TITLE: Qualification of UTAC Singapore for Bump Post-Test Production (Wafer Saw, Visual Inspection, Tape and Reel)

PROPOSED FIRST SHIP DATE: 31-Aug-2013

AFFECTED CHANGE CATEGORY(S):

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or <todd.manes@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or <ken.fergus@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

ON Semiconductor is pleased to announce a capacity expansion qualification of UTAC, located in Singapore, as an additional source for bump product post-test operations (wafer saw, visual inspection, tape and reel). These operations are currently performed at the ON Semiconductor facility located in Seremban, Malaysia. Upon expiration (or approval) of this FPCN, these operations may be performed at the ON Semiconductor, Malaysia facility or at the UTAC facility in Singapore.

UTAC is certified to be compliant to ISO-9001 and ISO-14001.

All production operations that occur through the test operation will remain unchanged. No changes to wafer fab, bumping facility, or production test facility are being made. Only the operations that occur after test are affected by this notification.

No changes to Finished Goods or product packing will be made.

**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20092****RELIABILITY DATA SUMMARY:**

Visual inspection and pick and place electronic map correlation have been performed between the existing production facility and UTAC to ensure all rejects will continue to be detected and removed from production.

Visual inspection results and pick and place electronic maps have been confirmed to be equivalent between the two facilities.

A summary of the qualification results can be made available upon request.

ELECTRICAL CHARACTERISTIC SUMMARY:

There are no changes to the electrical performance of products affected by this notification.

CHANGED PART IDENTIFICATION:

Country of origin on the reel and packing labels will indicate Singapore for devices processed through UTAC.

Country of origin on the reel and packing labels will indicate Malaysia for devices processed through the current production location of Seremban, Malaysia.

List of affected General Parts:

NCP1851AFCCT1G
NCP1851FCCT1G
NCP1852FCCT1G
NCP6335DFCT1G
NCP6335FFCT1G
NCP6335FFCT2G